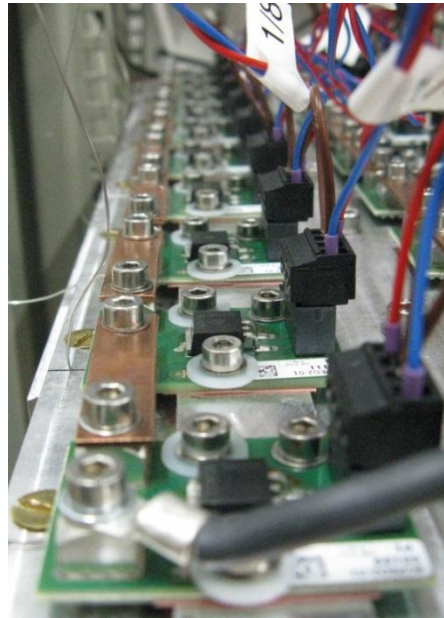


Reliability of Discrete Power Semiconductor Packages

- Project partner:
ECPE Engineering Center for Power Electronics GmbH (<http://www.ecpe.org/>)
and ECPE Principal Partners (e.g. SMA, Infineon)
- Contents:
 - Reliability analysis on discrete power semiconductor packages and systems
 - System analysis based on thermal and thermo-mechanical FE-simulations
 - Performing of power cycling tests as well as HTRB- and H3TRB-tests for evaluation of different discrete packages in comparison to power modules



D2Pak test systems during power cycling tests